

Harmonization Topics

1. Maintenance and service of components within the facility
 2. DCF definitions for communication protocols

1. Maintenance and service of components within the facility

- Facility-side provisions and limitations for servicing of coolant-charged components, such as manifolds, door heat exchanger, in-rack CDUs, etc.?
 - What would be a standard procedure for an OCP-compliant data center?

- What type of connection is recommended between rack and secondary/facility coolant loop?

1. Maintenance and service of components within the facility

- Service and replacing of heavier ACS components?
 - A door heat exchanger unit could be ~220lbs (including coolant; 330lbs max)
 - A single manifold could be ~30lbs
 - Mechanical assembly for a pair of manifolds could be 70~80lbs

- Considering possible aisle widths, how can ease of servicing/replacing be addressed?
 - Draining, unmounting, installation and priming?
 - Access to physical interfaces – coolant connections, power supply and communication cables?

1. Maintenance and service of components within the facility

- Containment and discharge of expelled coolant in the event of a leak?
 - Discharge from condensation pan at the bottom of Door HX assembly?

- Do requirements change based on location of coolant interface – overhead or underfloor/rack-bottom?

2. DCF definitions for communication protocols

- What would be a standard communications interface (port type and protocol) for an OCP-compliant data center to be a part of DCIMCOOLING domain?
 - Ports: RS485, ETH (RJ45)
 - Protocol: Modbus RTU/IP, SNMP v2/3, HTTP (webserver)

- Are there any other requirements specific to this area?